PCN Number:		20131216003							PCN Date:		12/27/2013		
Title: Moisture Sen			sitivity Level Change for OPA2363AIRSVR Package Device										
Customer Contact:			PCN Manager Phone: +1(214)480-6037						Dept:	Dept: Quality Service			
Proposed 1 st Ship Da)14	1 Ectimated Sample		ماد	e Availability:		Date provided at			
Filip Da					5/2//20	117	Loth				anabinty.	sa	mple request
Change Type:													
Assembly Site				Assembly Process					Assembly	nbly Materials			
Design				Electrical Specification						Tost Proco	Test Process		
Vafer Bump Site				Wafer Bump Material					Wafer Bump Process				
Water Dump Site			Η	Water Fab Materials						Wafer Fab Process			
				Part number change						Walci Fab Frocess			
PCN Details													
Description of Change:													
The Moisture Sensitivity Level of OPA2363AIRSVR Device will be changed from MSL1 to MSL2.													
						Moisture Sensitivity				ty			
			Device			Change From:				Change To:			
	OP		A2363AIRSVR				Level	1-260C Level 2-20			vel 2-260C		
Reason for Change:													
RSV packages are Qualified as MSL 1 260C. Customer recommends using MSL 2 260C for this specific device until MSL 1 260C Qualification is completed.													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Changes to product identification resulting from this PCN:													
Packing label on bag, box, reel will indicate: "MSL LVL:2"													
Product Affected:													
OPA2363AIRSVR													
Qualification Data													
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.													
Qual Vehicle : OPA2363AIRSV (MSL 2-260C)													
Package Construction Details													
Assembly Site:				HNT				Mold Comp	old Compound: 450176			76	
# Pins-Designator, Fan			nily	y: 16-RSV, QFN			Mount Com	ροι	ind	: 40017	400173		
Lead frame (Finish, Ba			se): NiPdAu, Cu			Bond Wire:			0.8Mil	0.8Mil Au			

Qualification: 🗌 Plan 🛛 Test Results						
Reliability Test	Conditions	Sample Size/Fail				
Electrical Characterization	-	Pass				
**Autoclave	121C, 2atm (96hrs)	80/0				
**T/C -55C/125C	-55C/+125C (1000 Cyc)	80/0				
**High Temp. Storage Bake	150C (1000 hrs)	80/0				
**HAST	130C, 85%RH (96 hrs)	88/0				
Solderability	Steam Age	22/0				
X-ray	Тор	88/0				
Manufacturability	(per mfg. Site specification)	Pass				
Moisture Sensitivity, L2	(Level 2, 260C)	12/0				
Notes **- Preconditioning sequence: Level 2-260C.						

Reference Qualification:

Qual Vehicle : TS3A44159RSV (MSL 1-260C)							
Package Construction Details							
Assembly Site:	HNT	Mold Compound:	45017	450176			
# Pins-Designator, Family:	16-RSV, QFN	Mount Compound:	40017	400173			
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8Mil Au				
Qualification: 🗌 Plan 🛛 Test Results							
Doliability Toot	Conditions		Sample Size/Fail				
Reliability Test	Conditions	Conditions		Lot#2	Lot#3		
**Steady-state Life Test	150C (300 hrs)	116/0	116/0	116/0			
**Biased HAST	130C/85%RH (77/0	77/0	77/0			
**Autoclave	121C, 2atm (96	77/0	77/0	77/0			
**T/C -65C/150C	-65C/+150C (5	77/0	77/0	77/0			
**High Temp. Storage Bake	150C (1000 hrs	77/0	77/0	77/0			
Solderability	Steam Age	22/0	22/0	22/0			
Flammability	(UL 94V-0)	5/0	5/0	5/0			
Flammability	(UL-1694)	5/0	5/0	5/0			
Flammability	(IEC 695-2-2)	(IEC 695-2-2)			5/0		
X-ray	Тор	5/0	5/0	5/0			
Salt Atmosphere	24 hrs	22/0	22/0	22/0			
Manufacturability	(per mfg. Site s	Pass	Pass	Pass			
Moisture Sensitivity, L1	(Level 1, 260C)	(Level 1, 260C)			12/0		
Notes **- Preconditioning sequence: Level 1-260C.							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com